

Abstract of the Disclosure:

A plurality of semiconductor chips each having an electrode surface are sequentially laminated and mounted. Initially, the electrode surfaces of the semiconductor chips are activated. Then, the semiconductor chips are positioned. Successively, the semiconductor chips are laminated and bonded by pressing such that a reaction layer is not formed or formation of the reaction layer is suppressed excessively. Finally, the semiconductor chips are entirely heated so as to form the reaction layer after lamination and bonding of all the semiconductor chips are completed.

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